

FH3415C+

P-Channel Enhancement Mode MOSFET

Description

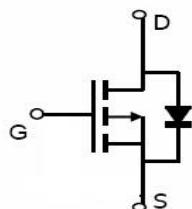
The FH3415C+ is the P-Channel enhancement mode MOSFET in a plastic package (SOT-23) using the Trench technology.

Applications

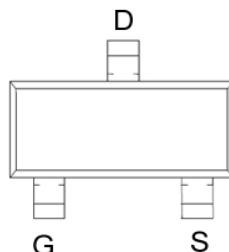
- LowSwitch
- DC-DCConverters
- Lithium-IonBatteryProtection

Features

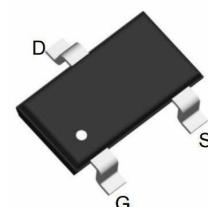
- $V_{DS} = -20V$; $I_D = -4.2A$
- $R_{DS(ON)}(\text{Typ.}) = 35m\Omega @ V_{GS} = -4.5V$
- $R_{DS(ON)}(\text{Typ.}) = 40m\Omega @ V_{GS} = -2.5V$
- TrenchTechnology
- FastSwitching
- High Power and Current Handling Capability
- SMD Package(SOT-23)
- MSL-3 compliant



Schematic diagram



Marking and Pin Assignment



SOT-23 top view

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-20	V
V_{GSS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-4.2	A
		$T_C = 100^\circ\text{C}$	-3.2	
I_{DM}	Pulsed Drain Current ^{note1}		-15	A
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	1.4	W
R_{JA}	Thermal Resistance, Junction to Ambient		74	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D = -250\mu\text{A}$	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20V, V_{GS} = 0V,$	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 12V$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.4	-0.55	-1.0	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note2	$V_{GS} = -4.5V, I_D = -4.1A$	-	35	40	$\text{m}\Omega$
		$V_{GS} = -2.5V, I_D = -3A$	-	40	55	
g_{FS}	Forward Transconductance	$V_{DS} = -5V, I_D = -2A$	-	6	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -10V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$	-	954	-	pF
C_{oss}	Output Capacitance		-	131	-	pF
C_{rss}	Reverse Transfer Capacitance		-	117	-	pF
Q_g	Total Gate Charge	$V_{DS} = -10V, I_D = -4.1A,$ $V_{GS} = -4.5V$	-	7.8	-	nC
Q_{gs}	Gate-Source Charge		-	1.2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1.6	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10V, I_D = -3.3A,$ $R_G = 1\Omega, V_{GEN} = -4.5V,$ $R_L = 1.2\Omega$	-	12	-	ns
t_r	Turn-on Rise Time		-	35	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	30	-	ns
t_f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	-4.2	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-15	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_S = -4.1A$	-	-	-1.2	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0V, I_S = -4.1A,$ $di/dt = 100A/\mu\text{s}$	-	20	-	ns
Q_{rr}	Reverse Recovery Charge		-	9	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Performance Characteristics

Figure 1: Output Characteristics

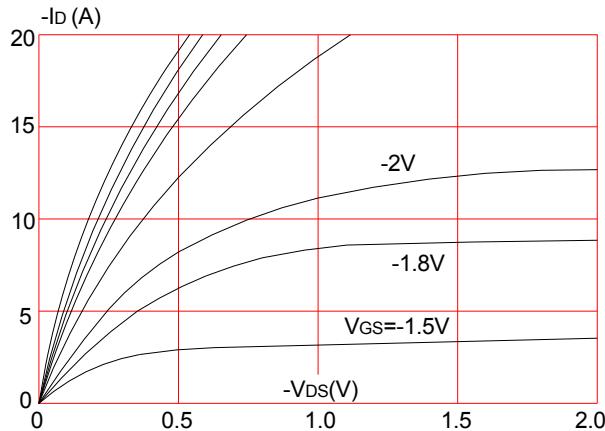


Figure 2: Typical Transfer Characteristics

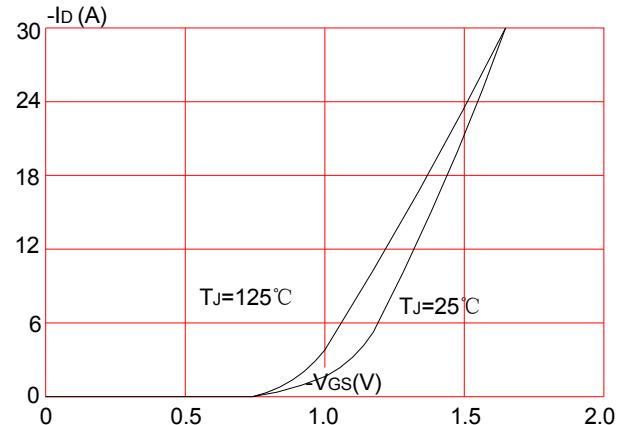


Figure 3: On-resistance vs. Drain Current

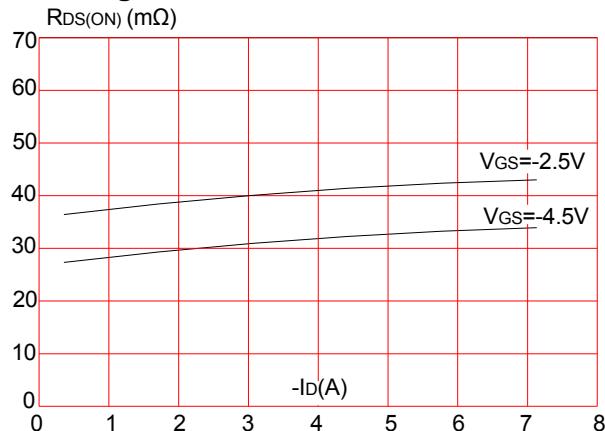


Figure 5: Gate Charge Characteristics

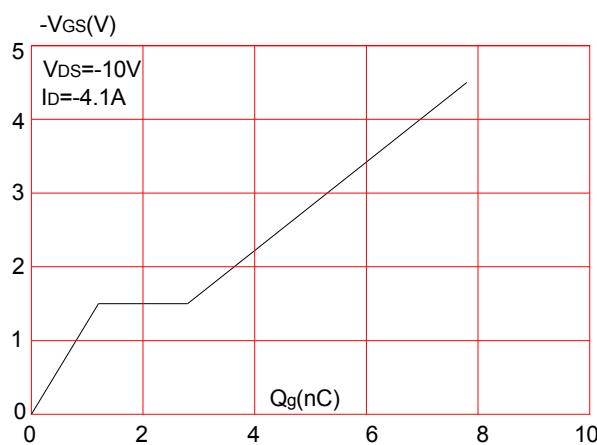


Figure 4: Body Diode Characteristics

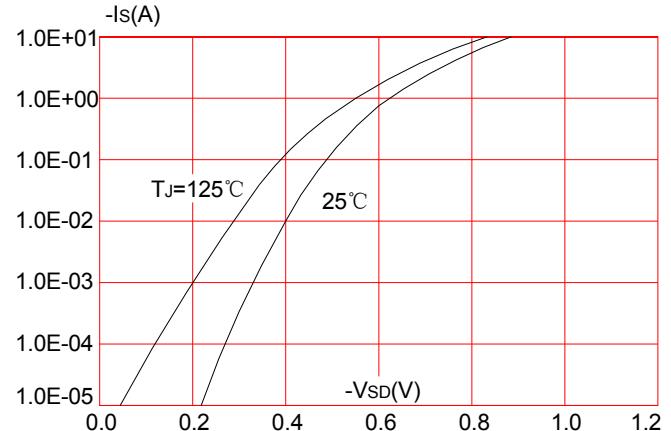


Figure 6: Capacitance Characteristics

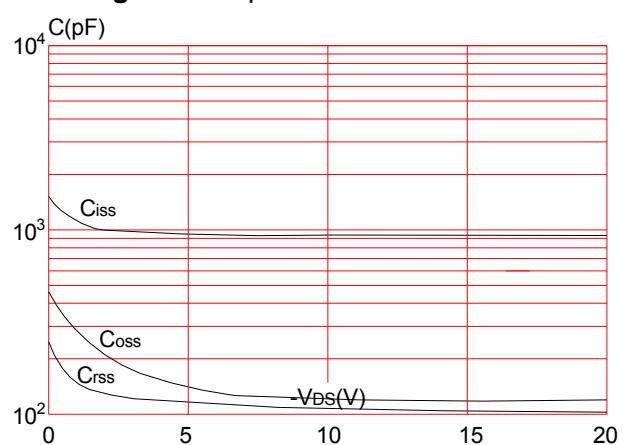


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

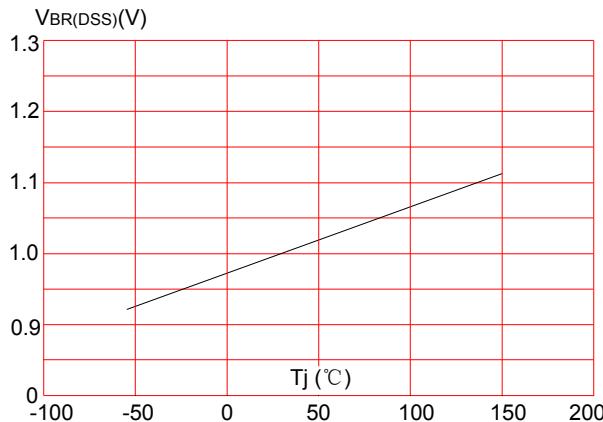


Figure 9: Maximum Safe Operating Area

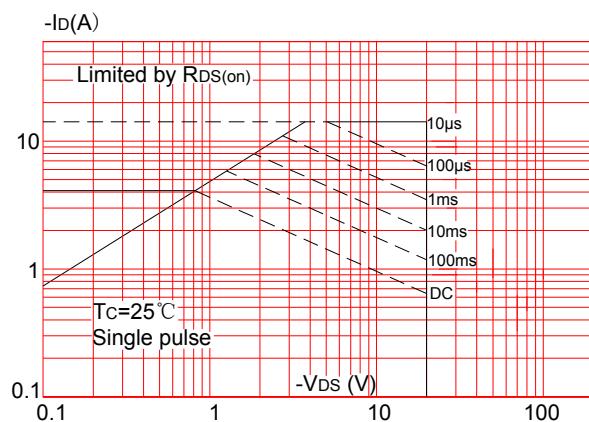


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient (SOT-23)

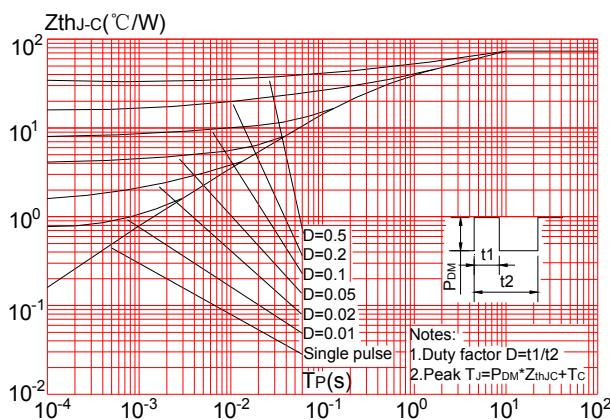


Figure 8: Normalized on Resistance vs. Junction Temperature

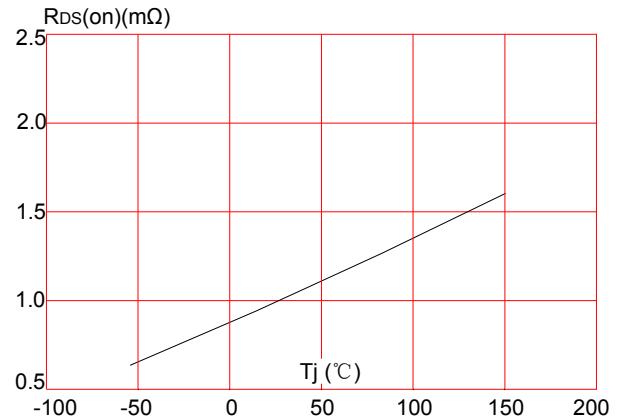
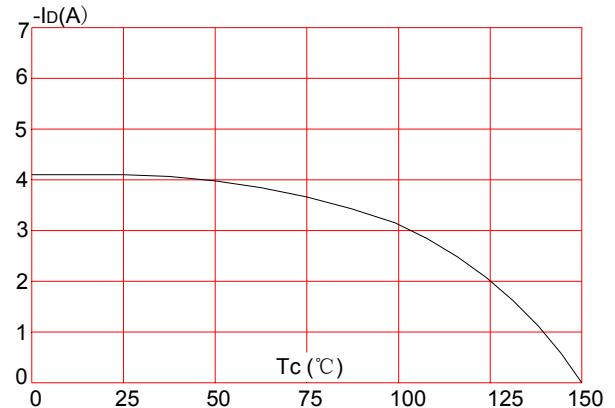


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Typical Electrical and Thermal Characteristics

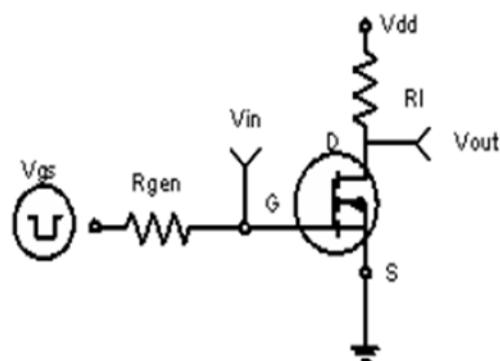


Figure 1: Switching Test Circuit

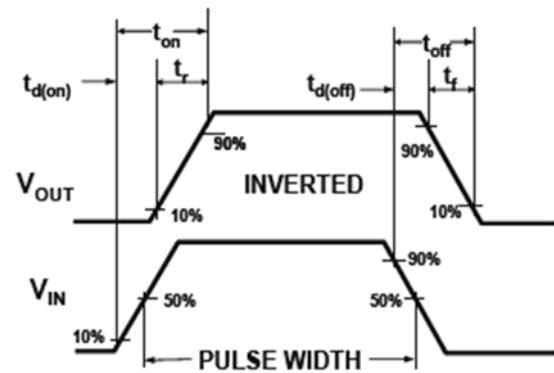


Figure 2: Switching Waveforms

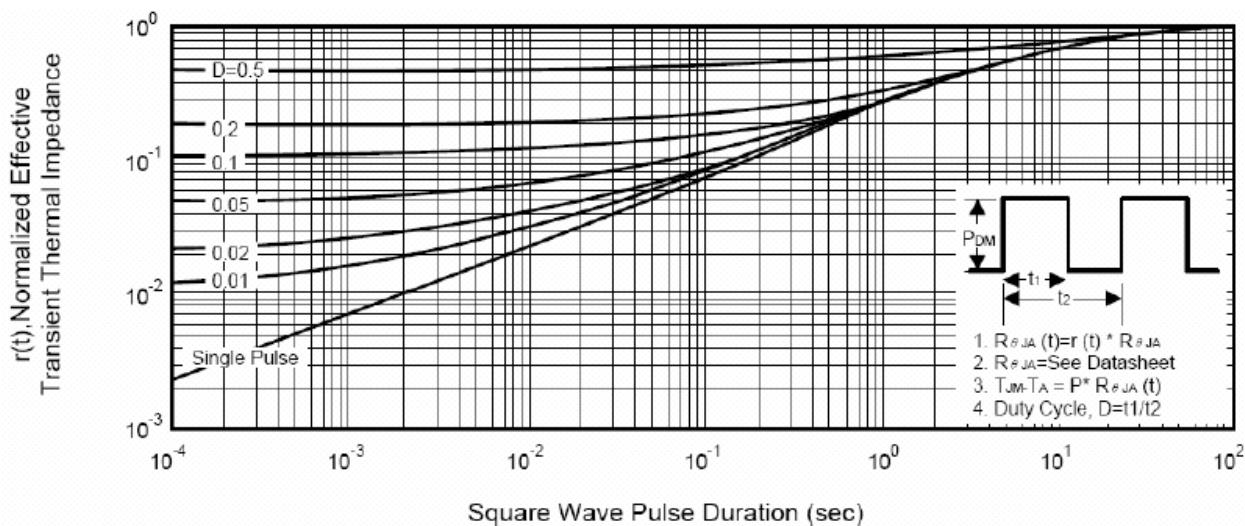
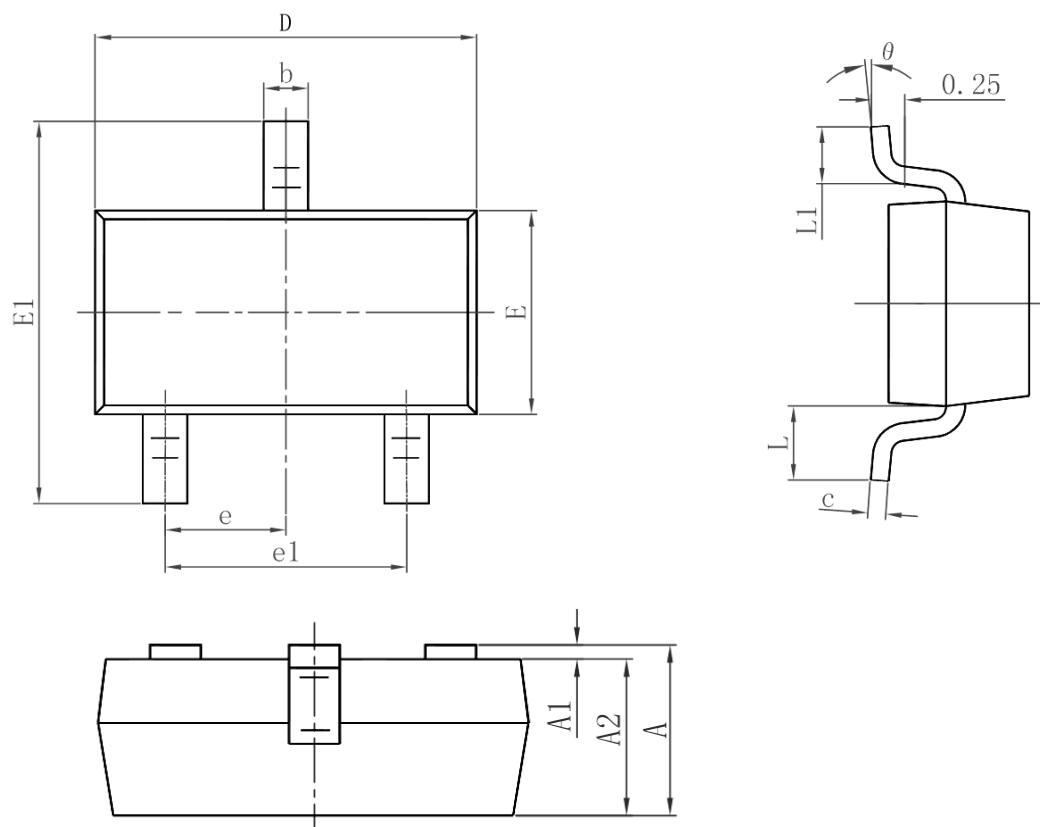


Figure 3: Normalized Maximum Transient Thermal Impedance

Package Dimensions : SOT-23



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
theta	0°	8°	0°	8°